

**FABRICATION NOTE :**

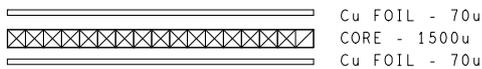
- 1:FABRICATE USING LATEST REVISION OF IPC-6012 CLASS 2 OR ABOVE
- 2:FABRICATE USING MASTER ARTWORK EVSTGAP2SiCSAN R1 FOR CIRCUIT PATTERN  
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN APPROVAL FROM AN AUTHORIZED STMicroelectronics REPRESENTATIVE
- 3:VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK ON BOTTOM SIDE, LOT OR JOB NUMBER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4:MATERIAL: FR4 RoHS COMPLIANT MINIMUM 130 C  
SEE "DETAIL 'A'" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 5:SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE PER IPC-SM-840 (LATEST LEVEL), CLASS H, COLOR: GREEN
- 6:FINISH: HASL LF RoHS COMPLIANT
- 7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED
- 8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10:DESIGNATED AREA OR INSPECTION AND TEST STAMP
- 11:ON SMB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE (MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 12:VENDOR TO PROVIDE BOARD STACK-UP FOR IMPEDANCE APPROVAL PRIOR TO BOARD FABBRICATION,STACK UP AND IMPEDANCE TO INCLUDE COPPER PLATING ON OUTER LAYERS.FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY VENDOR TO PROVIDE BOARD FOR IMPEDANCE TEST RESULTS AND COUPON
- 13:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 14:REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
- 15:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON SHORTS.
- 16:THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED SIZE	PLATED	QTY
A	13.0	PLATED	178
B	35.0	PLATED	7
C	43.31	PLATED	7
D	45.28	PLATED	10
E	55.0	PLATED	11
F	82.68	PLATED	2
G	128.0	NON-PLATED	4
⊘	70.0x40.0	PLATED	6

TOTAL HOLES: 225

**DETAIL 'A'**

LAYER BUILD UP  
(reference only)



(external Cu th are after plating)  
estimated total thickness 1600u

Finished Hole Tolerance - All units are in Inches -		
Finish Hole Diameter	Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter
0.008"-0.013"	+0.002/-FHS"	+/-0.002"
0.014"-0.063"	+/-0.003"	+/-0.002"
0.064"-0.156"	+/-0.004"	+/-0.003"
0.157"-0.250"	+/-0.007"	+/-0.004"
0.251"and up	+/-0.007"	+/-0.005"
0.125"	Non Plated Only	+0.003/-0.000"

REVISION DATE

	Description		Symbol	
	<b>EVSTGAP2SiCSAN</b>		STGAP2SiCSAN	
AMS-I&PC	AGRATE B. ITALY	DRILLING AND PROFILING		Group
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		linear	0 <10 >10 >50 >200	ANG. LES.
Drawn	date	midle	±0.1 ±0.2 ±0.3 ±0.5	Material
M. Rigo	02-Nov-2022	accurate	±0.05 ±0.1 ±0.15 ±0.25	
Approved	date	Treatment and surface finishing		